

PATENT ABSTRACTS OF JAPAN

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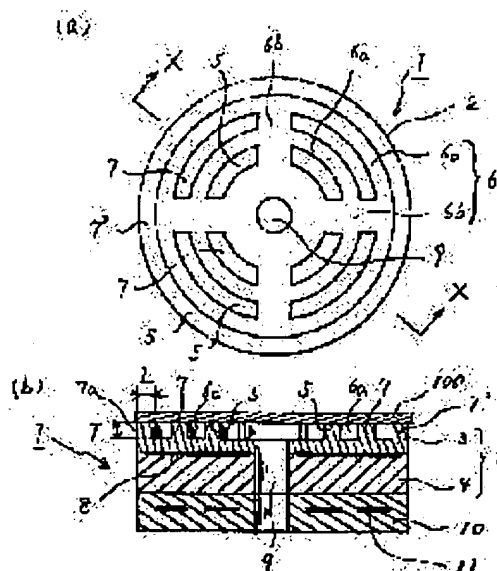
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(54) ELECTROSTATIC CHUCK

(57)Abstract:

PROBLEM TO BE SOLVED: To reduce the amount of adhesion of foreign matter to a semiconductor wafer, and also, heat a semiconductor wafer equally without leaking gas such as He, etc., supplied to the groove of a holding face into a chamber, in an electrostatic chuck where a groove is made on the surface of a dielectric layer.

SOLUTION: In an electrostatic chuck which is equipped with an electrostatic electrode 8 on one surface of the dielectric layer 3 consisting of ceramic or sapphire, and also has a groove 6 made on the other surface thereby being made uneven, and in which the apex of the projection 7 serves as a holding face, at least the width of the projection at the outermost periphery is made 1-20mm out of the projections 7 constituting the holding face, and besides the apex is made a smooth face 0.3 or under in average roughness (Ra) of center line. Moreover, the depth of the groove 6 provided at the above holding face is made 5 μ m or over.



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